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HITB \* V04 88-128666/19 \* J6 3070-486-A  
Electroless copper plating on copper-clad laminates by mounting  
laminates on jig and replacing one sheet with palladium-catalyst  
absorbing base plate.

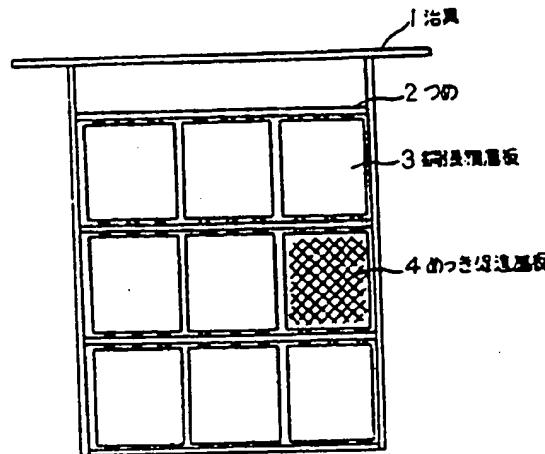
HITACHI CHEMICAL KK 11.09.86-JP-214536  
L03 M13 (30.03.88) C23c-18/38 H05k-03/18

11.09.86 as 214536 (93HW)

The laminates having more than one sheet perforated on the jig are  
mounted to give a planar form, where one piece of sheet among the  
laminates is replaced by a base plate to which Pd-catalyst is  
adsorbed well, and is mounted on the jig, making each mounted  
plate electrically conductive.

USE - With the method, electroless Cu plating can be applied to a  
number of perforated Cu-clad laminates efficiently. (3pp  
Dwg.No.1/1)  
N88-097753

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